






Integrated Device Technology, Inc.  
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## PRODUCT/PROCESS CHANGE NOTICE (PCN)

ATTACHMENT # 1 - PCN #: L0110-04

### Moisture Sensitivity Label for level 3

	<b>CAUTION</b> This Bag Contains <b>MOISTURE- SENSITIVE DEVICES</b>	<b>LEVEL</b> <b>3</b> If Blank, see adjacent bar code label
<ol style="list-style-type: none"><li>1. Calculated shelf life in sealed bag: 12 months at <math>&lt; 40^{\circ}\text{C}</math> and <math>&lt; 90\%</math> relative humidity (RH)</li><li>2. Peak package body temperature: <input type="checkbox"/> <math>225^{\circ}\text{C}</math> <input type="checkbox"/> <math>240^{\circ}\text{C}</math></li><li>3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must<ol style="list-style-type: none"><li>a) Mounted within <b>168 hours</b> of factory conditions <math>\leq 30^{\circ}\text{C}/60\%</math></li><li>b) Stored at <math>\leq 10\%</math> RH</li></ol></li><li>4. Devices require bake, before mounting, if:<ol style="list-style-type: none"><li>a) Humidity Indicator Card is <math>&gt;10\%</math> when read at <math>23 \pm 5^{\circ}\text{C}</math>,</li><li>b) 3a or 3b is not met.</li></ol></li><li>5. If baking is required, devices may be baked for 48 hours at <math>125 \pm 5^{\circ}\text{C}</math></li></ol>		
<p>Note: If device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J-STD-033 for bake procedure</p>		
Bag Seal Date : _____		
If Blank, see adjacent bar code label		
Note: Level and body temperature defined by IPC/JEDEC J-STD-020		